Texas Instruments DLP® - MEMS DMD Reverse Costing Analysis

by System Plus Consulting

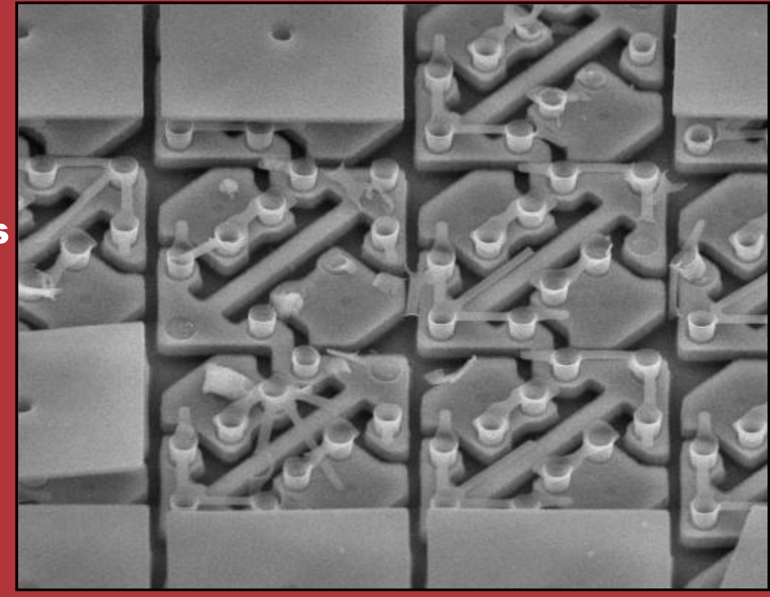
- **Analyze the cost of projects at the R&D level**
- **Enhance the negotiation power of purchasing managers**
- **Benchmark competitor's products**

System Plus Consulting is proud to publish the reverse costing report of the MEMS Digital Micromirror Device (DMD) for pico-projectors supplied by Texas Instruments. Based on a complete reverse engineering process the report provides an estimation of the production cost as well as the selling price of the circuit.

This Texas Instruments DLP® component is used in pico-projectors systems which can be integrated in phones or in pocket projectors. It uses a specific MEMS technology process using around 187K micromirrors with a 7x7µm area to perform a picture. The micromirrors are combined with a CMOS integrated circuit and SRAM memory for the control. The device uses a wafer level packaging technology and a ceramic substrate.

This report provides complete teardown of the MEMS with :

- Detailed photos
- Material analysis
- Schematic assembly description
- Manufacturing Process Flow
- In-depth economical analysis
- Manufacturing cost breakdown
- Selling price estimation



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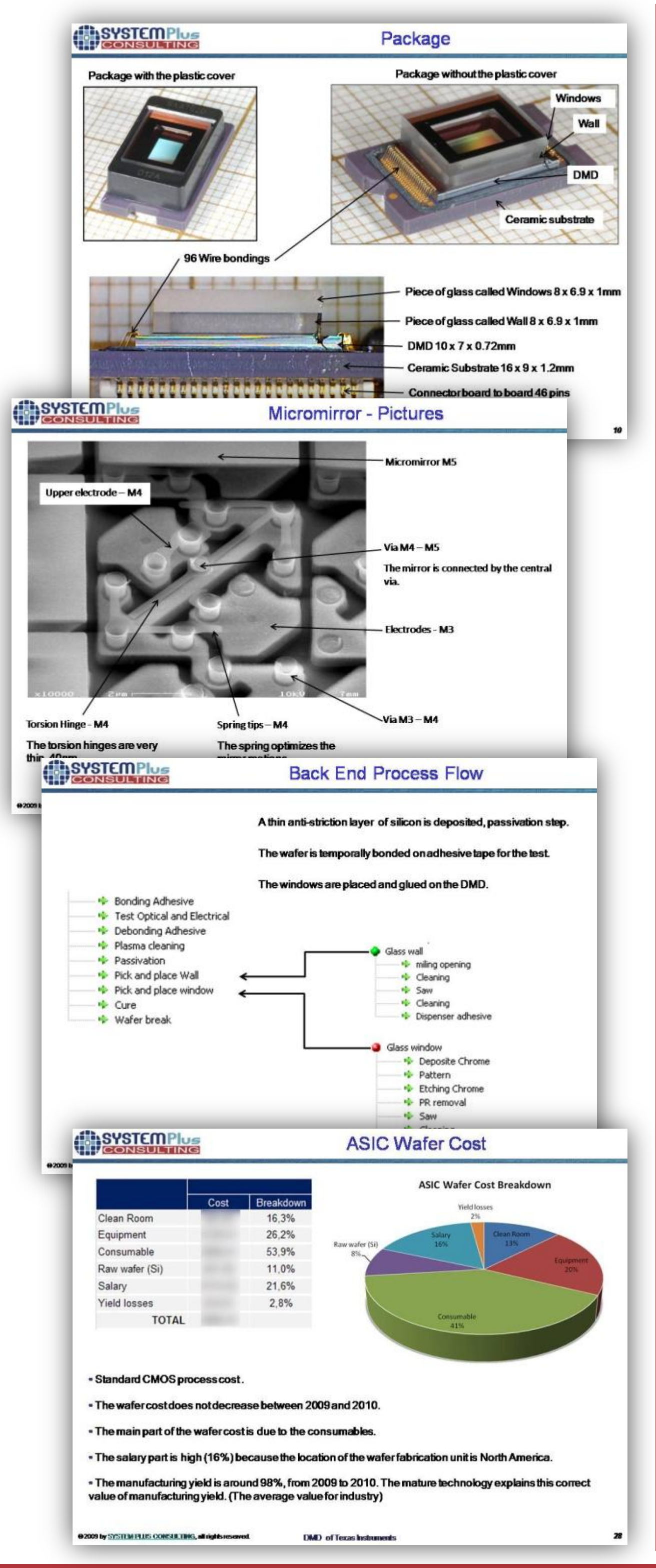

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Christiane BERGER, cberger@systemplus.fr,
Tel: +33 (0)240 18 09 16

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System Plus Consulting performs reverse costing analyses of

•Integrated circuits	Electronic boards
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•System In Package (SiP)	Smartcards

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